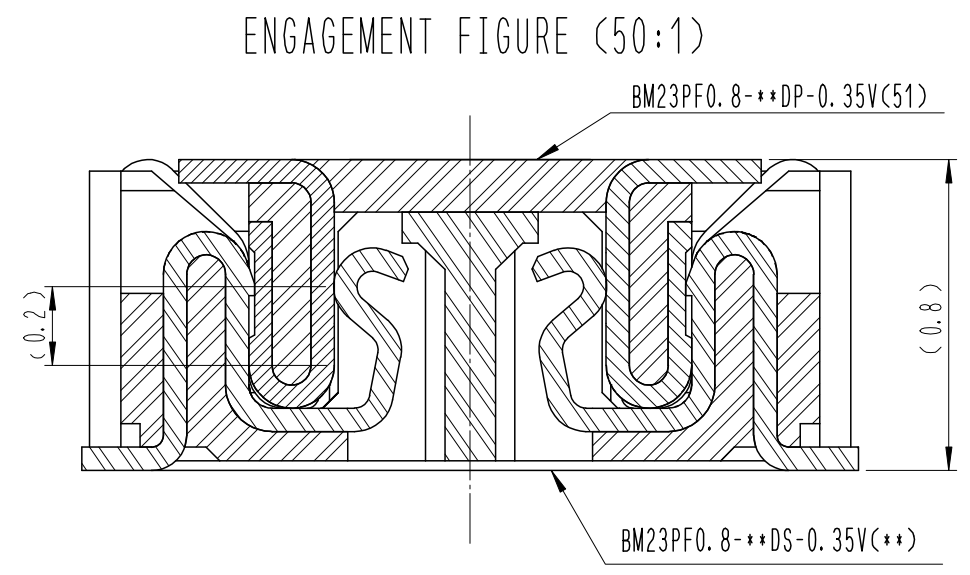
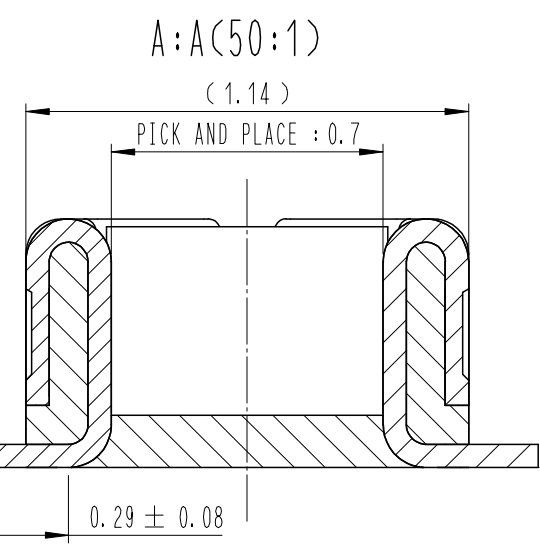
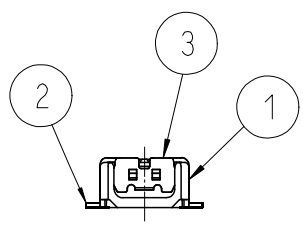
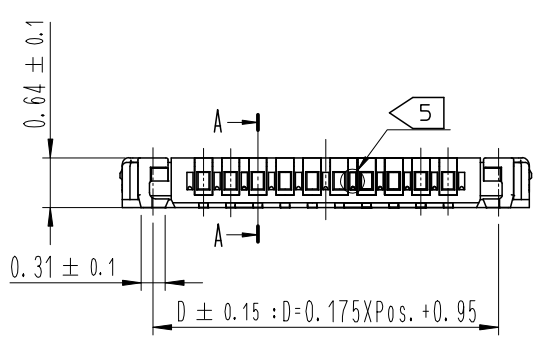
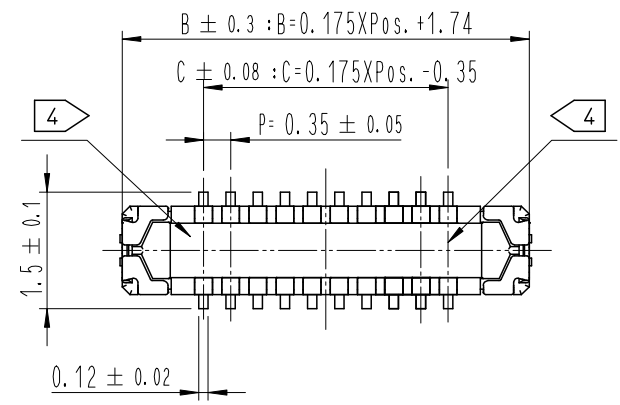


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COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
2	RE-6-0742	LYJ		JHW	16. 09 . 27	3	RE-6-1784	PSH		JHW	20. 04 . 09
3	RE-6-0806	MSH		JHW	17. 01 . 05						
1	RE-6-1137	KBJ		JHW	19. 02 . 14						



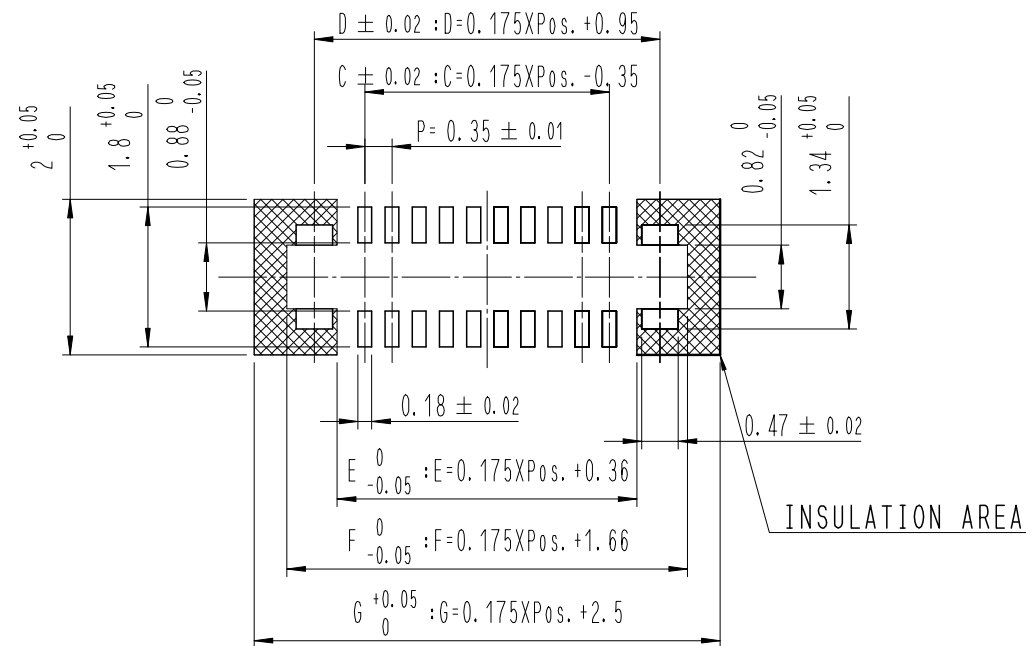
PART No.	CODE No.	POS.	B	C	D
BM23PF0.8-10DP-0.35V(51)	-	10	3.49	1.40	2.70
BM23PF0.8-14DP-0.35V(51)	-	14	4.19	2.10	3.40
BM23PF0.8-20DP-0.35V(51)	-	20	5.24	3.15	4.45
BM23PF0.8-24DP-0.35V(51)	-	24	5.94	3.85	5.15
BM23PF0.8-30DP-0.35V(51)	-	30	6.99	4.90	6.20
BM23PF0.8-40DP-0.35V(51)	-	40	8.74	6.65	7.95
BM23PF0.8-42DP-0.35V(51)	-	42	9.09	7.00	8.30
BM23PF0.8-44DP-0.35V(51)	-	44	9.44	7.35	8.65
BM23PF0.8-46DP-0.35V(51)	-	46	9.79	7.70	9.00
BM23PF0.8-50DP-0.35V(51)	-	50	10.49	8.40	9.70
BM23PF0.8-54DP-0.35V(51)	-	54	11.19	9.10	10.40
BM23PF0.8-60DP-0.35V(51)	-	60	12.24	10.15	11.45
BM23PF0.8-64DP-0.35V(51)	-	64	12.94	10.85	12.15

- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
  - 2. CONTACT PLATING SPECIFICATIONS.  
CONTACT AREA : GOLD 0.05 μm MIN.  
SMT LEAD : GOLD 0.05 μm MIN.  
UNDER PLATING : NICKEL 1 μm MIN.  
( SURFACE : SEALING )
  - 3. METAL FITTING PLATING SPECIFICATIONS.  
SMT LEAD : GOLD 0.05 μm MIN.  
UNDERPLATING : NICKEL 1 μm MIN.  
( SURFACE : SEALING )
  - 4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
  - 5. A PART OF THE WALL COULD BE NOTCHED.

4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	COOPER ALLOY		7	PS	CLEAR(REINFORCEMENT COLLAR)
2	COOPER ALLOY		6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
REMARKS			DRAWN	DESIGNED	CHECKED
			J. S. JANG	J. S. JANG	H. W. JO
			20.10.06	20.10.06	20.10.06
			APPROVED	RELEASED	
			H. W. JO	24.07.03	
			20.10.06		
CODE NO. (OLD)	DRAWING NO. EDC3-*****		PART NO. BM23PF0.8-**-DP-0.35V(51)		
SCALE 10:1	HRS HIROSE KOREA CO., LTD.		CODE NO. CL 66**-*****-51		
UNITS mm			1/3		

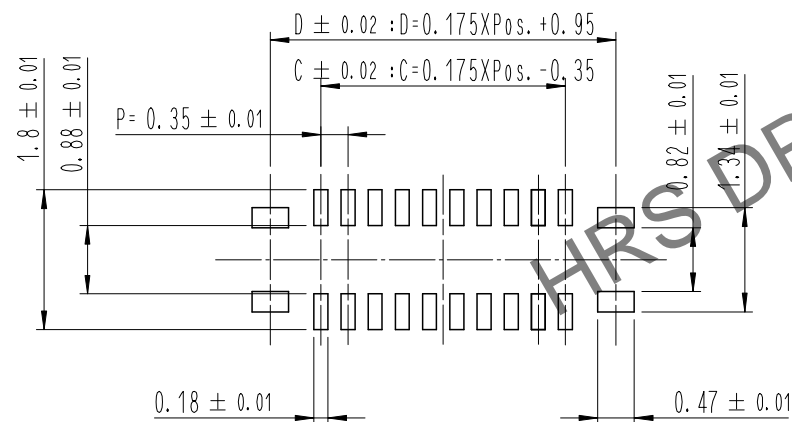
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7 RECOMMENDED PCB LAYOUT



RECOMMENDED METAL MASK DIMENSIONS

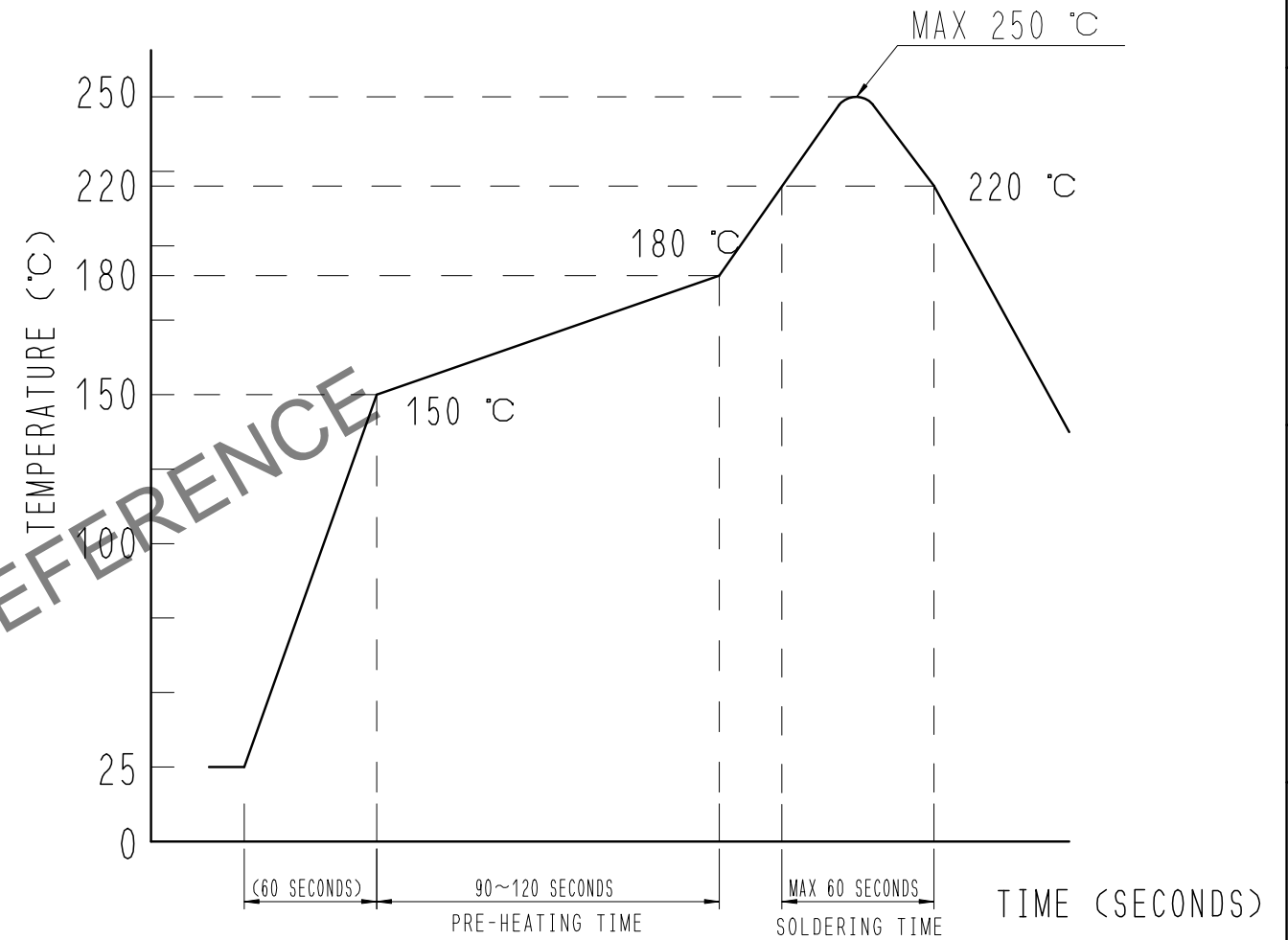
METAL MASK THICKNESS : 100 μm



2/3/4

POS.	C	D	E	F	G
10	1.40	2.70	2.11	3.41	4.25
14	2.10	3.40	2.81	4.11	4.95
20	3.15	4.45	3.86	5.16	6.00
24	3.85	5.15	4.56	5.86	6.70
30	4.90	6.20	5.61	6.91	7.75
40	6.65	7.95	7.36	8.66	9.50
42	7.00	8.30	7.71	9.01	9.85
44	7.35	8.65	8.06	9.36	10.20
46	7.70	9.00	8.41	9.71	10.55
50	8.40	9.70	9.11	10.41	11.25
54	9.10	10.40	9.81	11.11	11.95
60	10.15	11.45	10.86	12.16	13.00
64	10.85	12.15	11.56	12.86	13.70

6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N<sub>2</sub> REFLOW  
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.  
 1) REFLOW TIME  
 DURATION ABOVE 220°C: 60 SEC MAX.  
 (PEAK TEMPERATURE: 250°C MAX)  
 2) PRE-HEAT TIME  
 PRE-HEAT TEMPERATURE (MIN): 150°C  
 PRE-HEAT TEMPERATURE (MAX): 180°C  
 PRE-HEAT TIME: 90-120 SEC.

- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-*****	PART NO.	BM23PF0.8-***DP-0.35V(51)
	SCALE	10:1	CODE NO	CL 66**-*****-51
	UNITS	mm		2/3

